TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

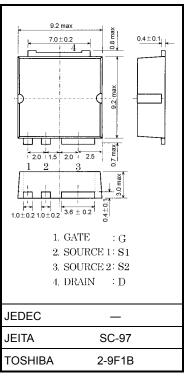
# 2SK3444

Switching Regulator, DC-DC Converter Applications Motor Drive Applications

- Low drain-source ON resistance:  $RDS(ON) = 65 m\Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 10 \text{ S} (typ.)$
- Low leakage current:  $IDSS = 100 \ \mu A (VDS = 200 \ V)$
- Enhancement mode:  $V_{th} = 3.0$  to 5.0 V ( $V_{DS} = 10$  V,  $I_D = 1$  mA)

# Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V <sub>DSS</sub>	200	V
Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ )		V <sub>DGR</sub>	200	V
Gate-source voltage		V <sub>GSS</sub>	±30	V
Drain current	DC (Note 1)	Ι <sub>D</sub>	25	А
	Pulse (Note 1)	I <sub>DP</sub>	100	A
Drain power dissipation (Tc = $25^{\circ}$ C)		PD	125	W
Single pulse avalanche energy (Note 2)		E <sub>AS</sub>	488	mJ
Avalanche current		I <sub>AR</sub>	25	А
Repetitive avalanche energy (Note 3)		E <sub>AR</sub>	12.5	mJ
Channel temperature		T <sub>ch</sub>	150	°C
Storage temperature range		T <sub>stg</sub>	-55 to 150	°C



Weight: 0.74 g (typ.)

Notice:

### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	1.00	°C/W

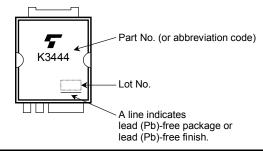
Note 1: Ensure that the channel temperature does not exceed 150°C.

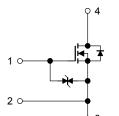
Note 2:  $V_{DD} = 50 \text{ V}, \text{ T}_{ch} = 25^{\circ}\text{C}$  (initial), L = 1.26 mH, I<sub>AR</sub> = 25 A, R<sub>G</sub> = 25  $\Omega$ 

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.

### Marking





Please use the S1 pin for gate input signal return. Make sure that the

# Electrical Characteristics (Note 4) (Ta = 25°C)

Cha	aracteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I <sub>GSS</sub>	$V_{GS}=\pm 25~V,~V_{DS}=0~V$			±10	μA
Drain cut-off curr	ent	I <sub>DSS</sub>	$V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	_		100	μA
Drain-source breat	akdown voltage	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	200		_	V
Gate threshold ve	oltage	V <sub>th</sub>	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$	3.0		5.0	V
Drain-source ON	resistance	R <sub>DS (ON)</sub>	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 12.5 \text{ A}$	_	65	82	mΩ
Forward transfer	admittance	Y <sub>fs</sub>	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 12.5 \text{ A}$	5	10		S
Input capacitance	9	C <sub>iss</sub>		_	2080		
Reverse transfer capacitance		C <sub>rss</sub>	$V_{DS} = 10 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}$		280		pF
Output capacitance	C <sub>oss</sub>	_		1060			
Switching time Fall time Turn-off time	Rise time	tr	$V_{GS} \stackrel{10 \text{V}}{\longrightarrow} I_D = 12.5 \text{ A}$	_	20	_	
	t <sub>on</sub>		_	40	_		
	Fall time	t <sub>f</sub>	R 0 4 4.7 0 R = 8.0	_	10	_	- ns
	Turn-off time	t <sub>off</sub>	$V_{DD} \simeq 100 \text{ V}$ Duty $\leq 1\%,  t_W = 10 \ \mu s$	_	40	_	
Total gate charge (gate-source plus gate-drain) Gate-source charge Gate-drain ("miller") charge		Qg	$V_{DD} \simeq 160 \text{ V}, \text{ V}_{GS} = 10 \text{ V},$ $I_D = 25 \text{ A}$	_	44		nC
		Q <sub>gs</sub>		_	21		
		Q <sub>gd</sub>	1	—	23	_	

Note 4: Connect the S1 pin and S2 pin together, and ground them except during switching time measurement.

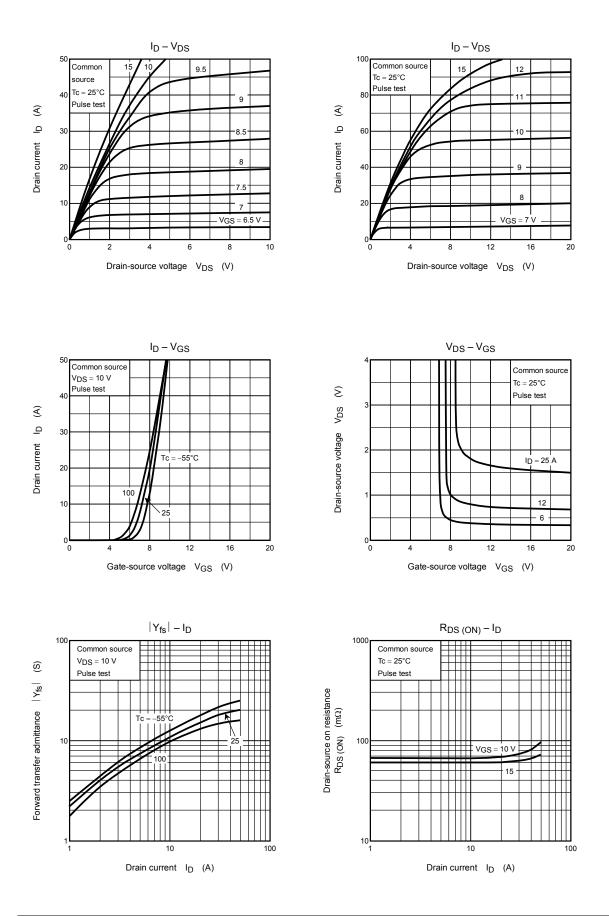
# Source-Drain Diode Ratings and Characteristics (Note 5) (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1, Note 5)	I <sub>DR</sub> 1	—	_	_	25	А
Pulse drain reverse current (Note 1, Note 5)	I <sub>DRP</sub> 1	—			100	А
Continuous drain reverse current (Note 1, Note 5)	I <sub>DR</sub> 2	_			1	A
Pulse drain reverse current (Note 1, Note 5)	I <sub>DRP</sub> 2	—			4	А
Forward voltage (diode)	V <sub>DS2F</sub>	$I_{DR1} = 25 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.5	V
Reverse recovery time	t <sub>rr</sub>	$I_{DR} = 25 \text{ A}, V_{GS} = 0 \text{ V}, $ $dI_{DR}/dt = 100 \text{ A}/\mu \text{s}$	_	290	_	ns
Reverse recovery charge	Q <sub>rr</sub>			2.2		μC

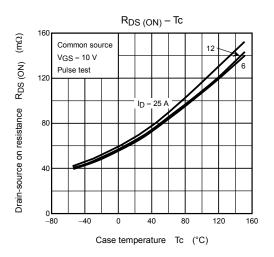
Note 5: I<sub>DR</sub>1, I<sub>DRP</sub>1: Current flowing between the drain and the S2 pin. Ensure that the S1 pin is left open. I<sub>DR</sub>2, I<sub>DRP</sub>2: Current flowing between the drain and the S1 pin. Ensure that the S2 pin is left open.

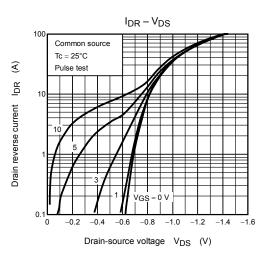
Unless otherwise specified, connect the S1 and S2 pins together, and ground them.

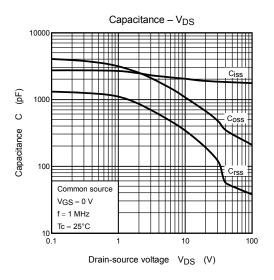
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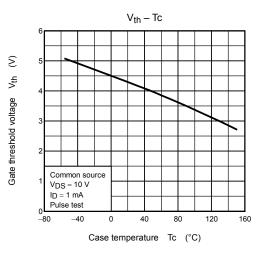


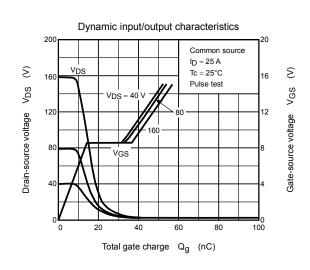
**TOSHIBA** 



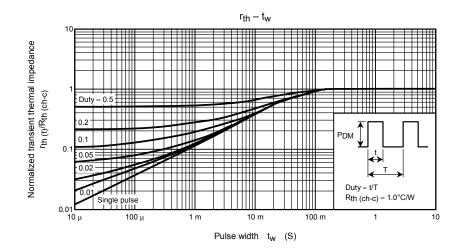


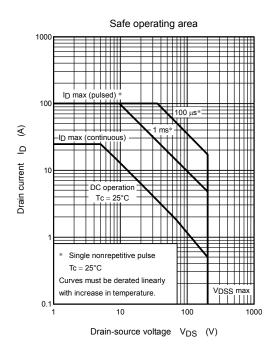


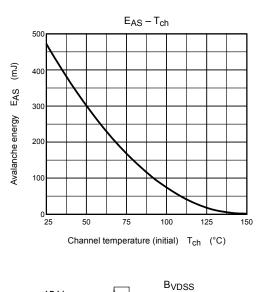


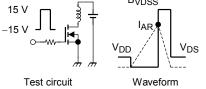


P<sub>D</sub> – Tc 200 Ś 160 Ч Drain power dissipation 120 80 40 10 0 40 80 120 160 200 Case temperature Tc (°C)









$R_G = 25 \Omega$	$E_{AB} = \frac{1}{2} \cdot   \cdot  ^2$	$\left(\frac{B_{VDSS}}{B_{VDSS}-V_{DD}}\right)$	
$V_{DD} = 50 \text{ V}, \text{ L} = 1.26 \text{ mH}$	LAS 2	(BVDSS-VDD)	

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